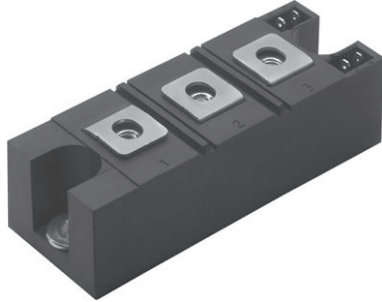





Thyristor/Thyristor, 160 A (INT-A-PAK Power Modules)



INT-A-PAK



FEATURES

- High voltage
- Electrically isolated by DBC ceramic (Al_2O_3)
- 3500 V_{RMS} isolating voltage
- Industrial standard package
- High surge capability
- Glass passivated chips
- Modules uses high voltage power thyristor/diodes in three basic configurations
- Simple mounting
- UL approved file E78996 
- Designed and qualified for multiple level
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- DC motor control and drives
- Battery charges
- Welders
- Power converters
- Lighting control
- Heat and temperature control

PRIMARY CHARACTERISTICS	
$I_{T(AV)}$	160 A
Type	Modules - thyristor, standard
Package	INT-A-PAK

MAJOR RATINGS AND CHARACTERISTICS			
SYMBOL	CHARACTERISTICS	VALUES	UNITS
$I_{T(AV)}$	85 °C	160	A
$I_{T(RMS)}$		355	
I_{TSM}	50 Hz	4870	
	60 Hz	5100	
I^2t	50 Hz	119	kA ² s
	60 Hz	108	
$I^2\sqrt{t}$		1190	kA ² \sqrt{s}
V_{RRM}	Range	1200, 1600	V
T_J	Range	-40 to +125	°C

ELECTRICAL SPECIFICATIONS

VOLTAGE RATINGS				
TYPE NUMBER	VOLTAGE CODE	V_{RRM}/V_{DRM} , MAXIMUM REPETITIVE PEAK REVERSE VOLTAGE V	V_{RSM}/V_{DSM} , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I_{RRM}/I_{DRM} AT 125 °C mA
VS-VSK.162	12	1200	1300	50
	16	1600	1700	



ON-STATE CONDUCTION					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum average on-state current at case temperature	$I_{T(AV)}$	180° conduction, half sine wave		160	A
				85	°C
Maximum RMS on-state current	$I_{T(RMS)}$	As AC switch		355	
Maximum peak, one-cycle on-state, non-repetitive surge current	I_{TSM}	t = 10 ms	No voltage reapplied	4870	A
		t = 8.3 ms		100 % V_{RRM} reapplied	
		t = 10 ms	Sine half wave, initial $T_J = T_J$ maximum		
		t = 8.3 ms		4300	
Maximum I^2t for fusing	I^2t	t = 10 ms	No voltage reapplied	119	kA ² s
		t = 8.3 ms		100 % V_{RRM} reapplied	
		t = 10 ms	84		
		t = 8.3 ms	76.7		
Maximum $I^2\sqrt{t}$ for fusing	$I^2\sqrt{t}$	t = 0.1 ms to 10 ms, no voltage reapplied		1190	kA ² √s
Low level value of threshold voltage	$V_{T(TO)1}$	(16.7 % $\times \pi \times I_{T(AV)} < I < \pi \times I_{T(AV)}$, T_J maximum)		0.8	V
High level value of threshold voltage	$V_{T(TO)2}$	(I > $\pi \times I_{T(AV)}$, T_J maximum)		0.98	
Low level value on-state slope resistance	r_{t1}	(16.7 % $\times \pi \times I_{T(AV)} < I < \pi \times I_{T(AV)}$, T_J maximum)		1.67	mΩ
High level value on-state slope resistance	r_{t2}	(I > $\pi \times I_{T(AV)}$, T_J maximum)		1.38	
Maximum on-state voltage drop	V_{TM}	$I_{TM} = \pi \times I_{T(AV)}$, $T_J = 25$ °C, 180° conduction		1.54	V
Maximum forward voltage drop	V_{FM}	$I_{TM} = \pi \times I_{T(AV)}$, $T_J = 25$ °C, 180° conduction		1.54	V
Maximum holding current	I_H	Anode supply = 6 V initial $I_T = 30$ A, $T_J = 25$ °C		200	mA
Maximum latching current	I_L	Anode supply = 6 V resistive load = 1 Ω Gate pulse: 10 V, 100 μs, $T_J = 25$ °C		400	

SWITCHING					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Typical delay time	t_{gd}	$T_J = 25$ °C	Gate current = 1 A, $dI_g/dt = 1$ A/μs $V_d = 0.67$ % V_{DRM}	1	μs
Typical rise time	t_{gr}			2	
Typical turn-off time	t_q	$I_{TM} = 300$ A, - $dI/dt = 15$ A/μs; $T_J = T_J$ maximum $V_R = 50$ V; $dV/dt = 20$ V/μs; gate 0 V, 100 Ω		50 to 200	

BLOCKING					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum peak reverse and off-state leakage current	I_{RRM} , I_{DRM}	$T_J = 125$ °C		50	mA
RMS insulation voltage	V_{INS}	50 Hz, circuit to base, all terminals shorted, t = 1 s		3500	V
Critical rate of rise of off-state voltage	dV/dt	$T_J = T_J$ maximum, exponential to 67 % rated V_{DRM}		1000	V/μs



TRIGGERING					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum peak gate power	P_{GM}	$t_p \leq 5$ ms, $T_J = T_J$ maximum		12	W
Maximum average gate power	$P_{G(AV)}$	$f = 50$ Hz, $T_J = T_J$ maximum		3	
Maximum peak gate current	I_{GM}	$t_p \leq 5$ ms, $T_J = T_J$ maximum		3	A
Maximum peak negative gate voltage	$-V_{GT}$			10	V
Maximum required DC gate voltage to trigger	V_{GT}	$T_J = -40$ °C	Anode supply = 6 V, resistive load; $R_a = 1$ Ω	4	
		$T_J = 25$ °C		2.5	
		$T_J = T_J$ maximum		1.7	
Maximum required DC gate current to trigger	I_{GT}	$T_J = -40$ °C		270	mA
		$T_J = 25$ °C		150	
		$T_J = T_J$ maximum		80	
Maximum gate voltage that will not trigger	V_{GD}	$T_J = T_J$ maximum, rated V_{DRM} applied		0.3	V
Maximum gate current that will not trigger	I_{GD}			10	mA
Maximum rate of rise of turned-on current	di/dt	$T_J = T_J$ maximum, $I_{TM} = 400$ A rated V_{DRM} applied		300	A/ μ s

THERMAL AND MECHANICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum junction operating temperature range	T_J			-40 to +125	°C
Maximum storage temperature range	T_{Stg}			-40 to +150	
Maximum thermal resistance, junction to case per junction	R_{thJC}	DC operation		0.16	K/W
Maximum thermal resistance, case to heat sink per module	R_{thCS}	Mounting surface, smooth, flat and greased		0.05	
Mounting torque ± 10 %	IAP to heat sink busbar to IAP	A mounting compound is recommended and the torque should be rechecked after a period of 3 hours to allow for the spread of the compound. Lubricated threads.		4 to 6	Nm
Approximate weight				200	g
Case style				7.1	oz.
				INT-A-PAK	

ΔR CONDUCTION PER JUNCTION											
DEVICES	SINUSOIDAL CONDUCTION AT T_J MAXIMUM					RECTANGULAR CONDUCTION AT T_J MAXIMUM					UNITS
	180°	120°	90°	60°	30°	180°	120°	90°	60°	30°	
VS-VSK.162	0.0030	0.0031	0.0032	0.0033	0.0034	0.0029	0.0036	0.0039	0.0041	0.0040	K/W

Note

- Table shows the increment of thermal resistance R_{thJC} when devices operate at different conduction angles than DC

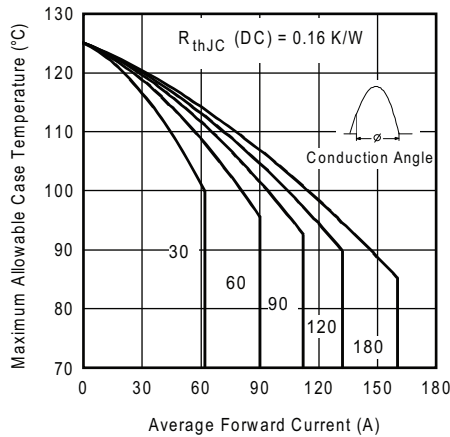


Fig. 1 - Current Ratings Characteristics

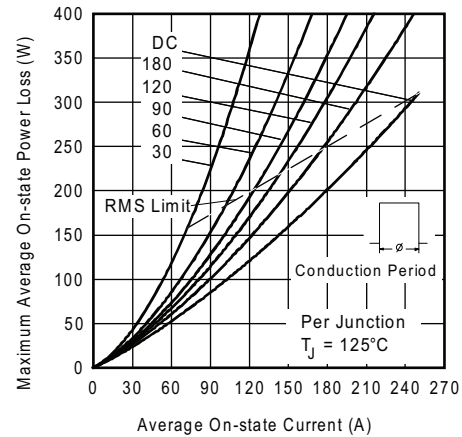


Fig. 4 - On-State Power Loss Characteristics

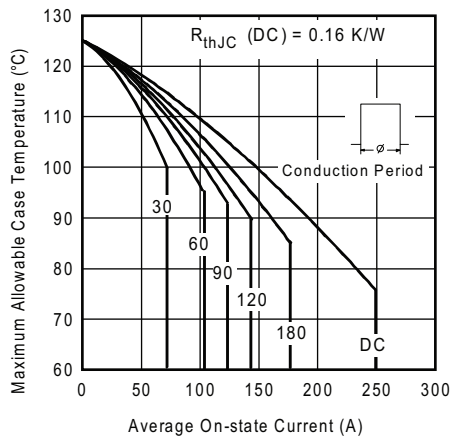


Fig. 2 - Current Ratings Characteristics

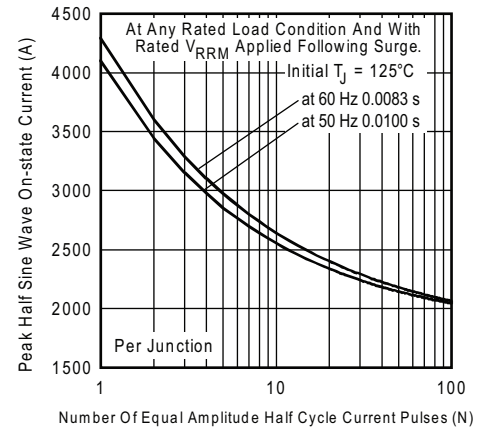


Fig. 5 - Maximum Non-Repetitive Surge Current

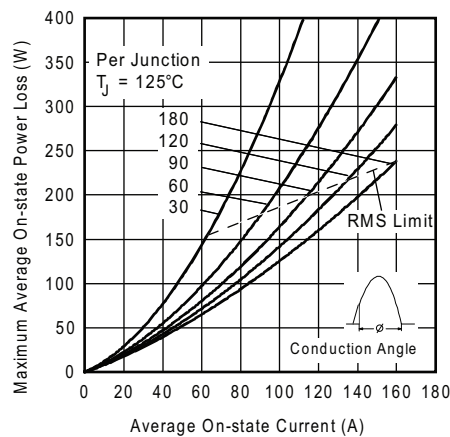


Fig. 3 - On-State Power Loss Characteristics

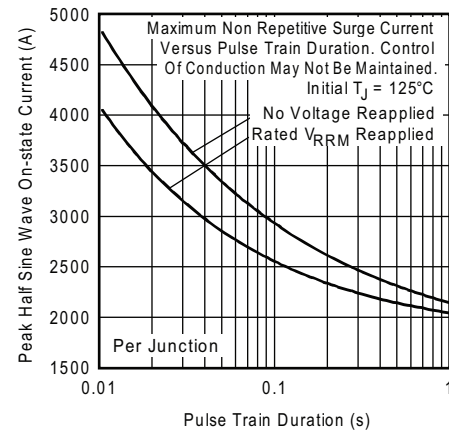


Fig. 6 - Maximum Non-Repetitive Surge Current

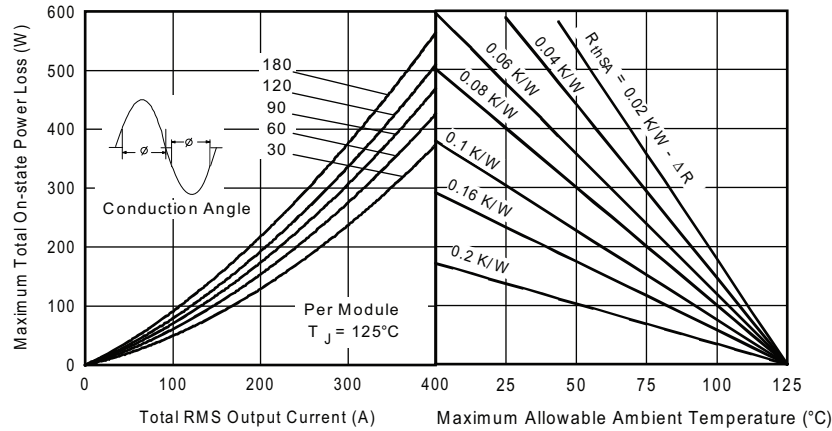


Fig. 7 - On-State Power Loss Characteristics

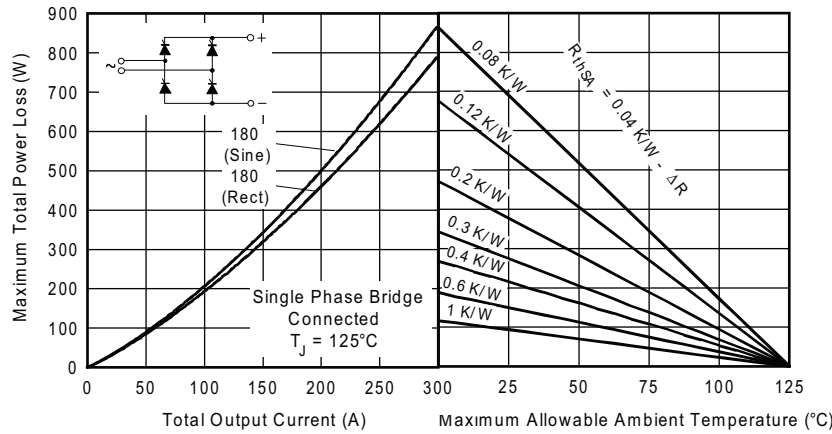


Fig. 8 - On-State Power Loss Characteristics

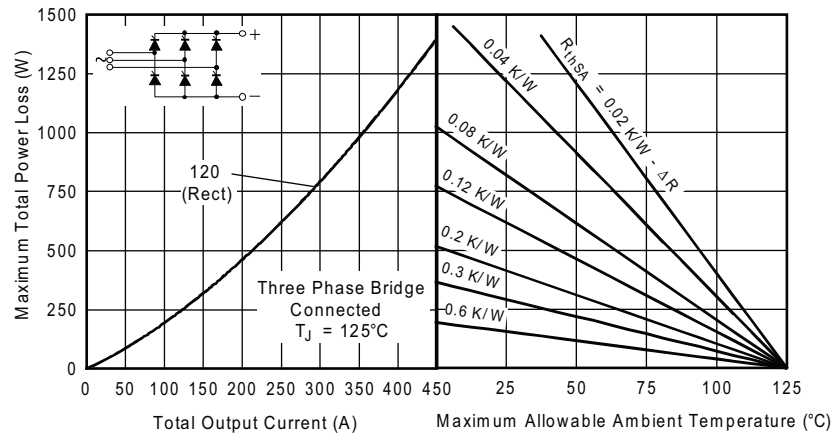


Fig. 9 - On-State Power Loss Characteristics

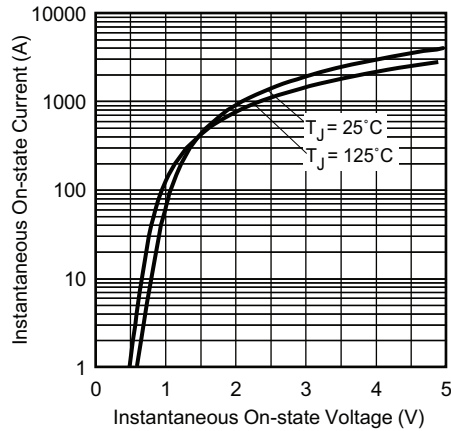


Fig. 10 - On-State Voltage Drop Characteristics

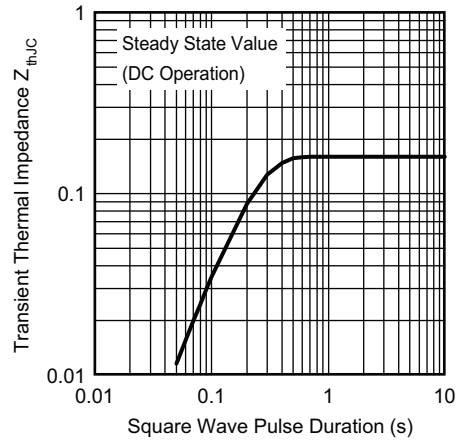


Fig. 11 - Thermal Impedance Z_{thJC} Characteristics

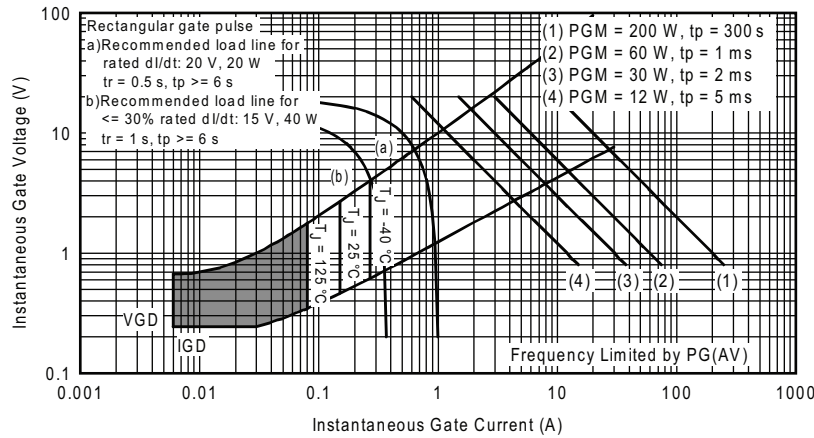


Fig. 12 - Gate Characteristics

ORDERING INFORMATION TABLE

Device code	VS-VS	KU	162	16	PbF
	①	②	③	④	⑤
	1	-	Vishay Semiconductors product		
	2	-	Circuit configuration		
	3	-	Current rating: $I_{T(AV)}$		
	4	-	Voltage code x 100 = V_{RRM}		
	5	-	PbF = Lead (Pb)-free		

Note

- To order the optional hardware go to www.vishay.com/doc?95172

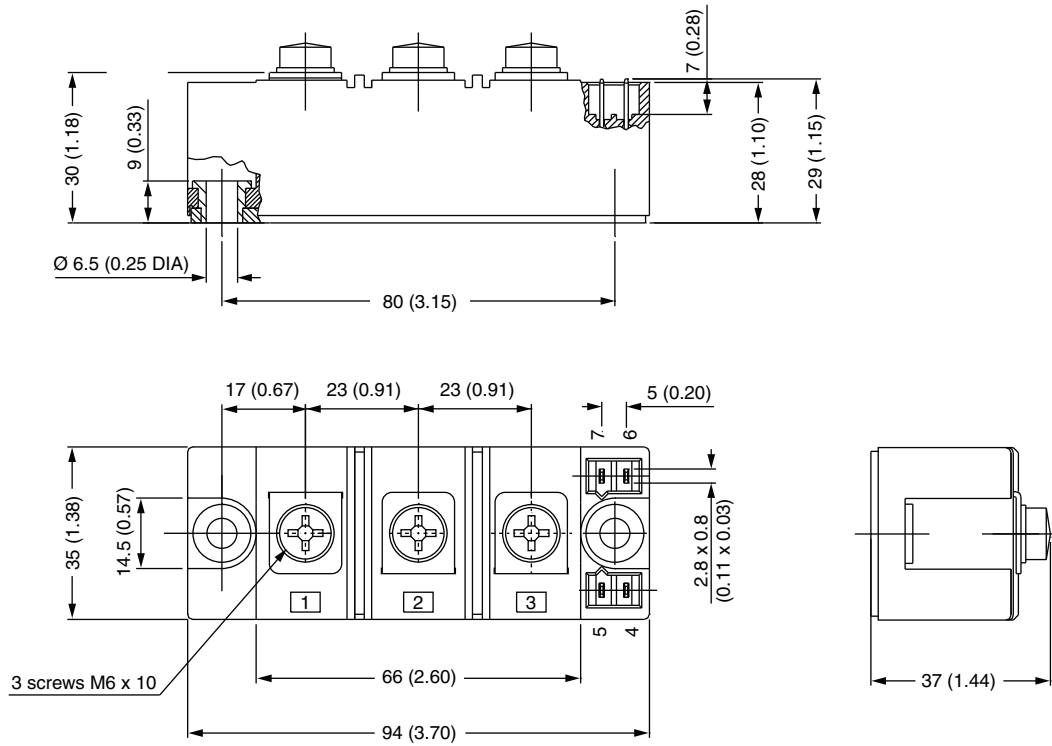


CIRCUIT CONFIGURATION		
CIRCUIT DESCRIPTION	CIRCUIT CONFIGURATION CODE	CIRCUIT DRAWING
Two SCRs common cathodes	U	
Two SCRs common anodes	V	

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95067

INT-A-PAK IGBT/Thyristor

DIMENSIONS in millimeters (inches)





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